

IN THE CLAIMS:

Please accept amended claims 10, 45, 51, 55 and 57 as follows:

1-9. (canceled)

10. (currently amended) A contact structure of a wire, comprising:
a wire of a conductive material on a substrate, wherein the wire is made of a conductive material including aluminum-based material;
an inter-layer reaction layer formed on the wire and including at least Al_xSi_x or inter-metallic compound comprising Al, wherein the inter-metallic compound is formed by depositing a metal layer on the wire and annealing the metal layer; and
a conductive layer directly connected to the wire via the inter-layer reaction layer.

11. – 13. (canceled)

14. (original) The contact structure of claim 10, wherein the conductive layer is made of a transparent conductive material of indium zinc oxide.

15. (original) The contact structure of claim 10, further comprising an insulating layer having a contact hole exposing the inter-layer reaction layer between the wire and the conductive layer.

16. – 44. (canceled)

45. (currently amended) A thin film transistor array panel, comprising:
a gate wire made of a first conductive material on an insulating substrate;
a gate insulating layer covering the gate wire;
a semiconductor layer formed on the gate insulating layer;
a data wire made of a second conductive material on the gate insulating layer and the semiconductor layer;

a passivation layer covering the data wire;

an inter-layer reaction layer formed on the gate wire and the data wire, wherein the inter-layer reaction layer includes inter-metallic compound comprising Al and the inter-metallic compound is formed by depositing a metal layer on the gate wire and the data wire and annealing the metal layer; and

a transparent conductive layer pattern electrically connected to the gate wire or the data wire through a contact hole of the gate insulating layer or the passivation layer, wherein the transparent conductive layer pattern is electrically connected to the gate wire or the data wire via the inter-layer reaction layer.

46. (original) The thin film transistor array panel of claim 45, wherein the first and second conductive material include a metal of aluminum-based material.

47. (original) The thin film transistor array panel of claim 45, wherein the insulating layer and the passivation layer are made of silicon-nitride.

48. (original) The thin film transistor array panel of claim 45, wherein the transparent conductive layer pattern is made of indium zinc oxide.

49. (previously presented) The thin film transistor array panel of claim 45, wherein the gate wire includes a gate line, a gate electrode connected to the gate line, and a gate pad which is connected to the gate line and receives a signal from an external circuit, and the data wire includes a data line, a source electrode connected to the data line, a drain electrode which is separated from the source electrode and opposite to the source electrode with respect to the gate electrode, and a data pad which is connected to the data line and receives a signal from an external circuit.

50. (original) The thin film transistor array panel of claim 45, wherein the inter-layer reaction layer includes silicon or transition metal.

51. (currently amended) A wiring contact structure, comprising:

a first wire formed of a conductive material, wherein the first wire contains aluminum; and

a second wire formed on and in contact with the first wire, the second wire comprising:

a first conductive layer formed of a conductive material; and

a second conductive layer sandwiched between the first wire and the first conductive layer and containing Al_xSi_x or inter-metallic compound comprising Al, wherein the inter-metallic compound is formed by depositing a metal layer on the first wire and annealing the metal layer, and

wherein the first conductive layer is directly connected to the first wire via the second conductive layer.

52. – 53. (canceled)

54. (previously presented) The wiring contact structure of claim 51, wherein the first conductive layer is formed of a transparent conductive material.

55. (currently amended) The contact structure of claim 10, wherein the inter-layer reaction layer ~~includes Al_xSi_x and~~ directly contacts the conductive layer.

56. (previously presented) The contact structure of claim 10, wherein the inter-layer reaction layer is formed only on a portion of the wire exposed through a contact hole.

57. (currently amended) The wiring contact structure of claim 51, wherein the second conductive layer ~~includes Al_xSi_x and~~ directly contacts the first conductive layer.

58. (previously presented) The wiring contact structure of claim 51, wherein the second conductive layer is formed only on a portion of the first wire exposed through a contact hole.